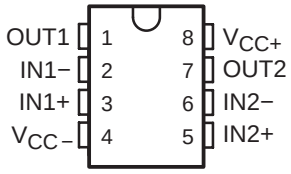
SLOS453A − DECEMBER 2004 − REVISED JANUARY 2005

- **Single/Dual Power-Supply Operation**
- **High Output Current . . . 70 mA, V_{CC+} = 5 V**
- **Wide Operating Voltage . . . 3 V to 15 V (Single Supply)**
- **Ideal for Headphone Drivers**

D (SOIC), P (PDIP), OR PW (TSSOP) PACKAGE
(TOP VIEW)



description/ordering information

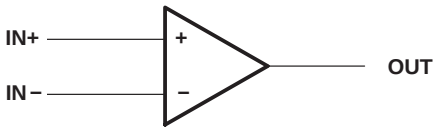
The TL3414A device is a dual operational amplifier that can be operated with single or dual power supplies. In addition to high gain and high output voltage swing, it is capable of driving a 70-mA load, making it ideally suited for simple, low-cost audio-amplifier applications, such as headphone amplifiers in DVD and CDRW applications.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	PDIP (P)	Tube of 50	TL3414AIP	TL3414AIP
	SOIC (D)	Tube of 75	TL3414AID	Z3414A
		Reel of 2500	TL3414AIDR	
	TSSOP (PW)	Tube of 150	TL3414AIPW	Z3414A
		Reel of 2000	TL3414AIPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol (each amplifier)



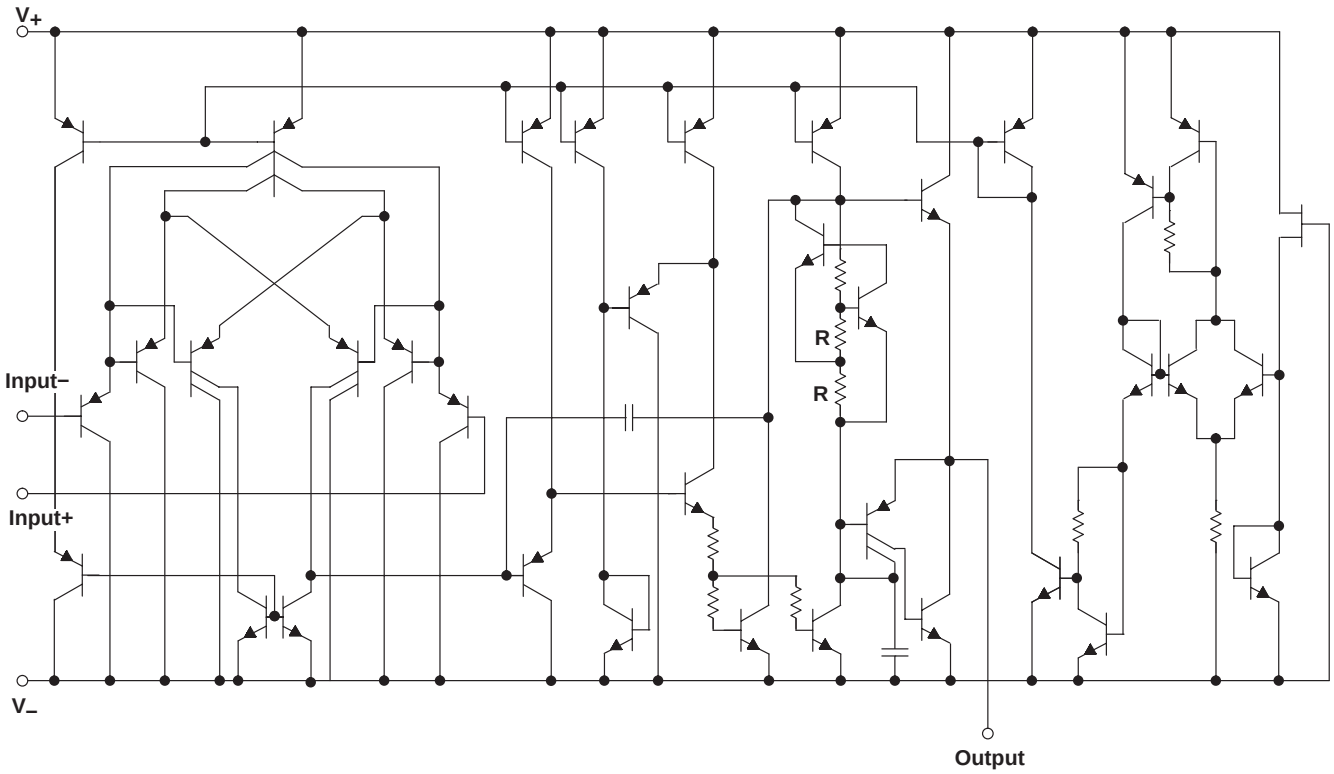


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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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simplified schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC+} (single supply)	15 V
Supply voltage, V_{CC-} (single supply)	0 V
Supply voltage, V_{CC+} (dual supply)	7.5 V
Supply voltage, V_{CC-} (dual supply)	−7.5 V
Supply voltage, (V_{CC-} to V_{CC+})	15 V
Input voltage, either input (see Note 1)	V_{CC-} or V_{CC+}
Input current (see Note 2)	±10 mA
Duration of output short circuit (see Note 3)	Unlimited
Package thermal impedance, θ_{JA} (see Notes 4 and 5): D package	97°C/W
P package	85°C/W
PW package	149°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	−40°C to 125°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES:
1. The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
2. Excessive input current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
3. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
4. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
V_{CC}	Supply voltage (single supply)	3	15	V
V_{CC+}	Supply voltage (dual supply)	1.5	7.5	V
V_{CC-}	Supply voltage (dual supply)	−1.5	−7.5	V
V_{ID}	Differential input voltage		15	V
V_I	Input voltage	−0.3	15	V
T_A	Operating free-air temperature range	−40	85	°C

DC electrical characteristics, V_{CC+} = 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	R_S = 0 Ω		2	5	mV
I_{IO}	Input offset current			15	100	nA
I_{IB}	Input bias current			300	600	nA
A_{VD}	Large-signal differential voltage amplification	R_L = 2 kΩ	77	100		dB
V_{ICR}	Common-mode input voltage range		V_{CC+} − 2 V			V
V_{OM}	Output voltage swing	R_L > 2 kΩ, V_{CC+} = 5 V	3.5			V
		I_O = 70 mA, V_{CC+} = 5 V	3.2			
CMRR	Common-mode rejection ratio		70	79		dB
k_{SVR}†	Supply-voltage rejection ratio		80	90		dB
I_{CC}	Supply current (all amplifiers)	R_L = open circuit (full temperature range)	3	4	6	mA

† Measured with $V_{CC\pm}$ differentially and simultaneously varied from 5 V to 8.6 V

AC electrical characteristics, V_{CC+} = 5 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain		0.83	V/μs
GBW	Gain bandwidth product		1.1	MHz
V_n	Equivalent input noise voltage	f = 1 kHz	18	nV/√Hz

DC electrical characteristics, V_{CC+} = 8.6 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	R_S = 0 Ω		2	5	mV
I_{IO}	Input offset current			15	100	nA
I_{IB}	Input bias current			300	600	nA
A_{VD}	Large-signal differential voltage amplification	R_L = 2 kΩ	88	105		dB
V_{ICR}	Common-mode input voltage range		V_{CC+} − 2 V			V
V_{OM}	Output voltage swing	R_L > 2 kΩ, V_{CC+} = 8.6 V	7			V
		I_O = 70 mA, V_{CC+} = 8.6 V	6.7			
CMRR	Common-mode rejection ratio		80	90		dB
k_{SVR}†	Supply-voltage rejection ratio		80	90		dB
I_{CC}	Supply current (all amplifiers)	R_L = open circuit (full temperature range)	3	4	6	mA

† Measured with $V_{CC\pm}$ differentially and simultaneously varied from 5 V to 8.6 V

AC electrical characteristics, V_{CC+} = 8.6 V, V_{CC-} = 0 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain		1.3	V/μs
GBW	Gain bandwidth product		2	MHz
V_n	Equivalent input noise voltage	f = 1 kHz	18	nV/√Hz

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TL3414AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3414AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3414AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3414AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3414AIP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL3414AIPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL3414AIPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3414AIPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3414AIPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL3414AIPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

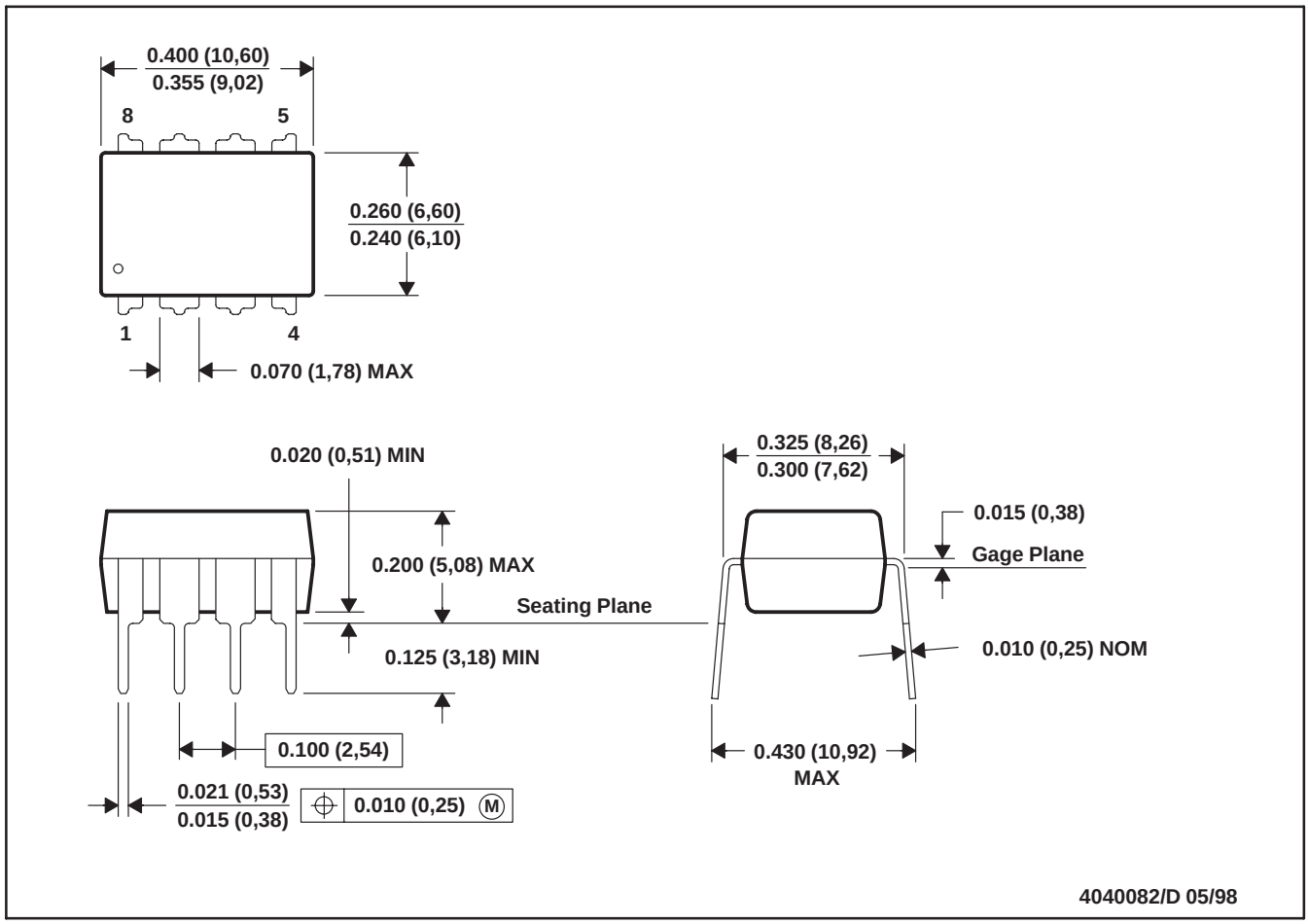
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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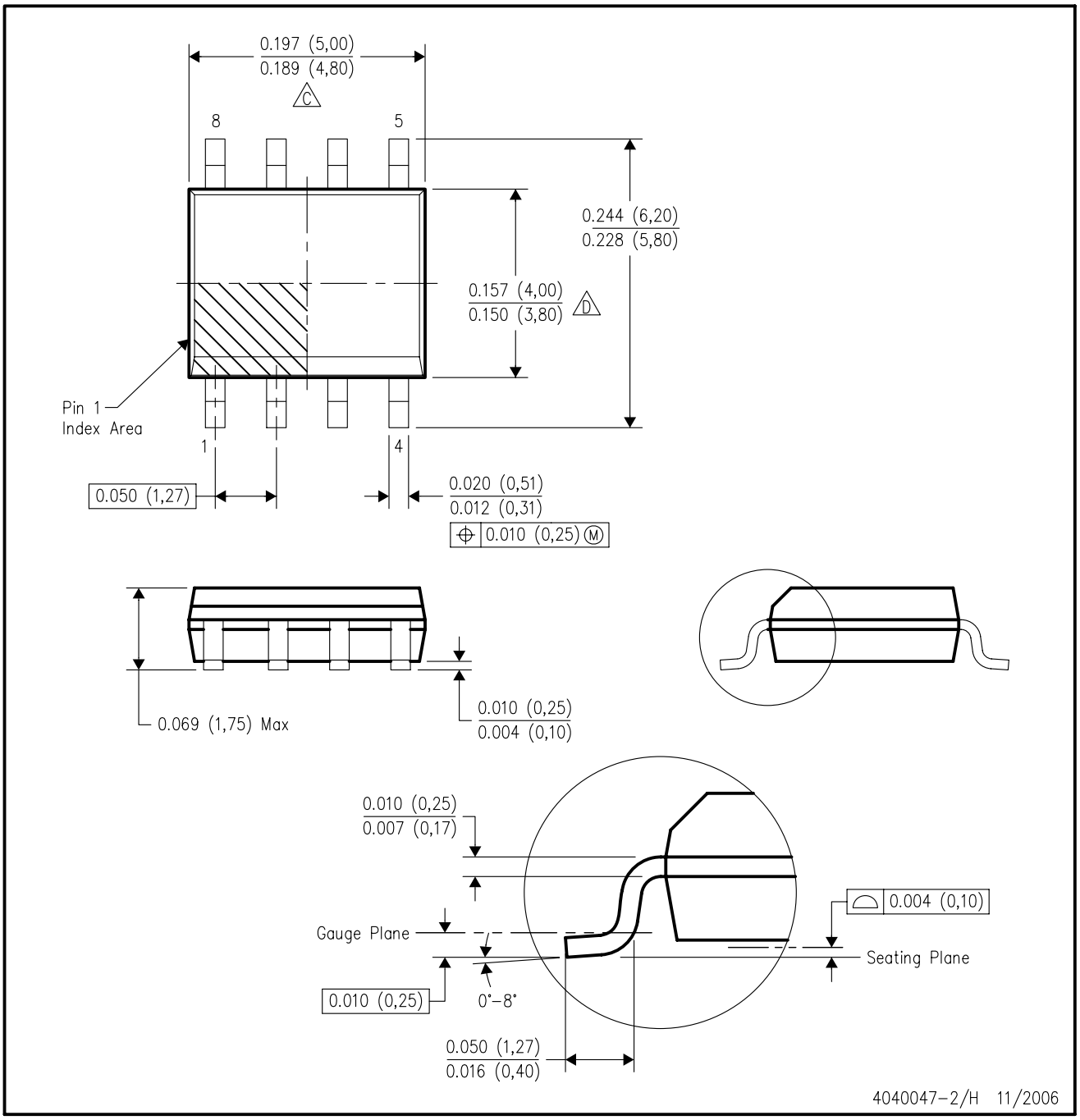
P (R-PDIP-T8) **PLASTIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

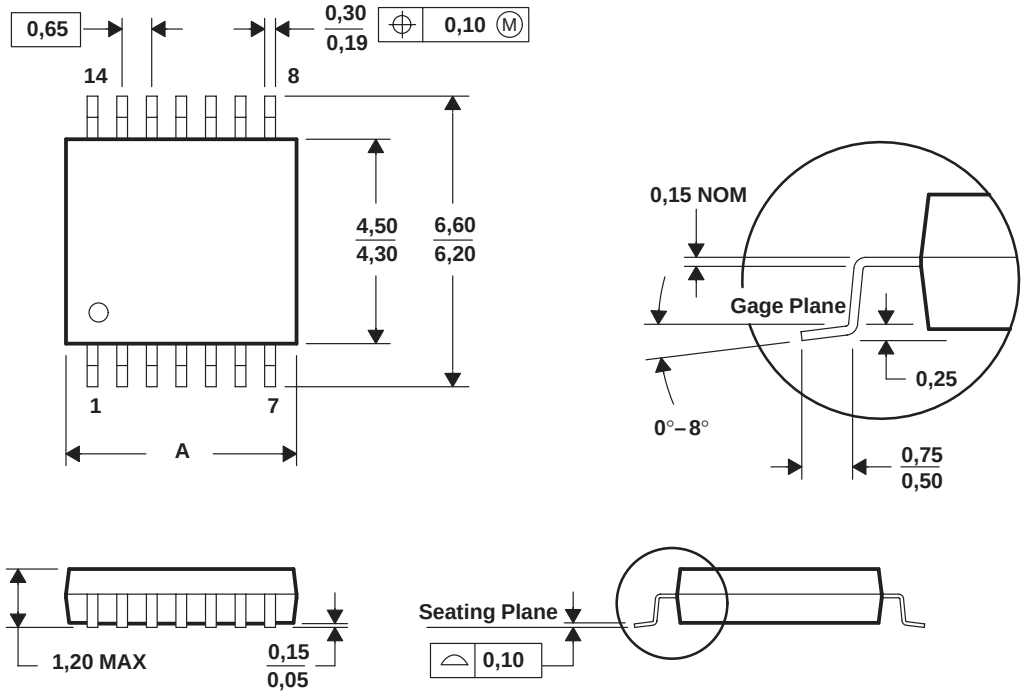
D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AA.

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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